

DATASHEET

HITACHI
2SK2225

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2SK2225

Silicon N-Channel MOS FET

HITACHI

ADE-208-140
1st. Edition

Application

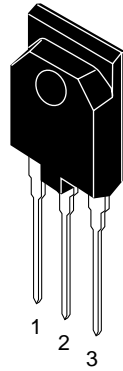
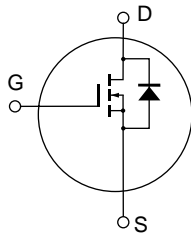
High speed power switching

Features

- High breakdown voltage ($V_{DSS} = 1500 \text{ V}$)
- High speed switching
- Low drive current
- No Secondary Breakdown
- Suitable for Switching regulator, DC-DC converter

Outline

TO-3PFM



1. Gate
2. Drain
3. Source

Absolute Maximum Ratings (Ta = 25°C)

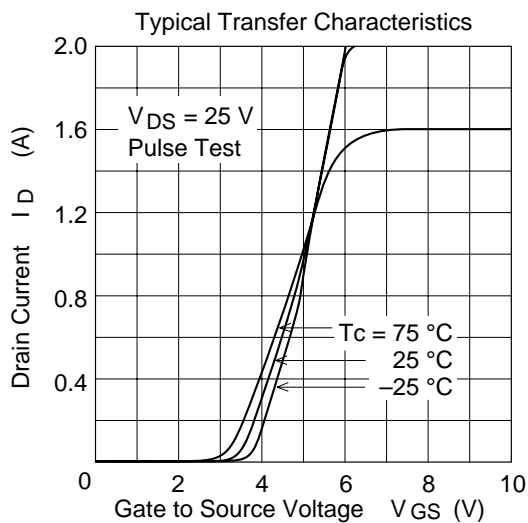
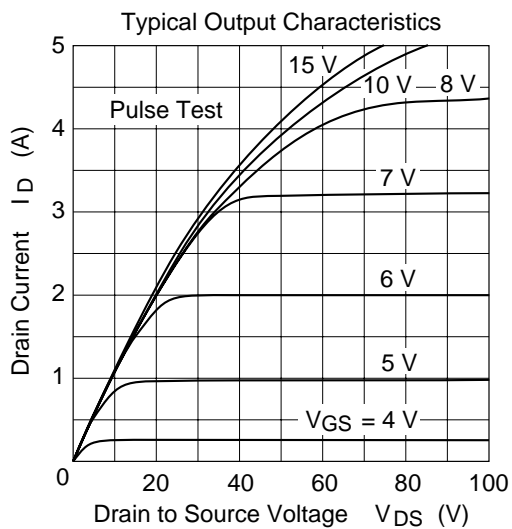
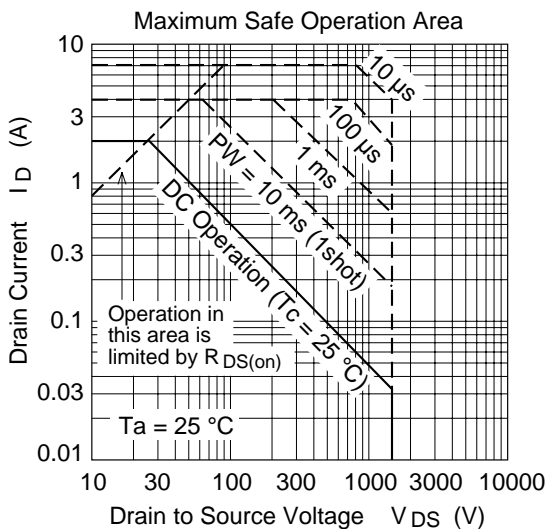
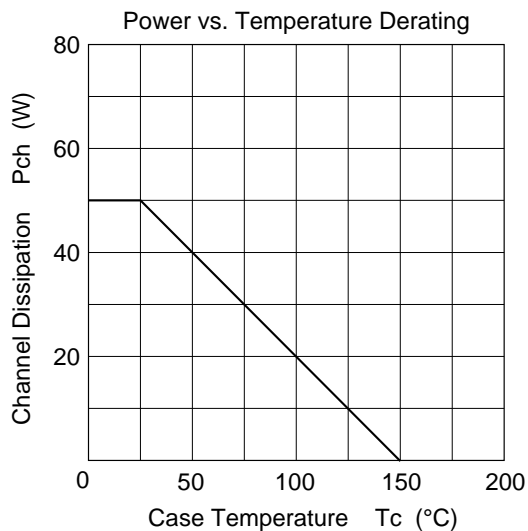
Item	Symbol	Ratings	Unit
Drain to source voltage	V_{DSS}	1500	V
Gate to source voltage	V_{GSS}	±20	V
Drain current	I_D	2	A
Drain peak current	$I_{D(pulse)}^{*1}$	7	A
Body to drain diode reverse drain current	I_{DR}	2	A
Channel dissipation	Pch^{*2}	50	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes 1. $PW \leq 10 \mu s$, duty cycle $\leq 1\%$
 2. Value at $T_c = 25^\circ C$

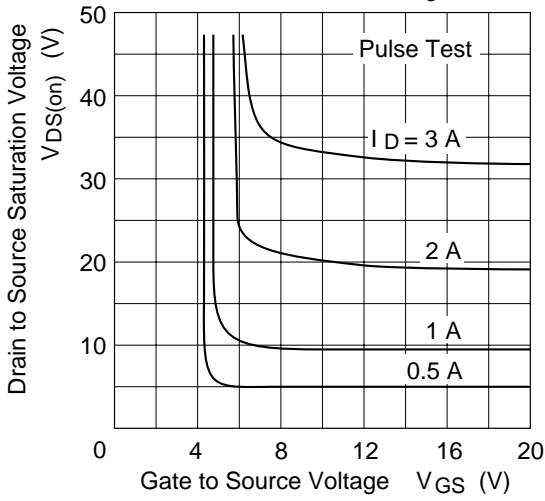
Electrical Characteristics (Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	1500	—	—	V	$I_D = 10 \text{ mA}$, $V_{GS} = 0$
Gate to source leak current	I_{GSS}	—	—	±1	μA	$V_{GS} = \pm 20 \text{ V}$, $V_{DS} = 0$
Zero gate voltage drain current	I_{DSS}	—	—	500	μA	$V_{DS} = 1200 \text{ V}$, $V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	2.0	—	4.0	V	$I_D = 1 \text{ mA}$, $V_{DS} = 10 \text{ V}$
Static drain to source on state resistance	$R_{DS(on)}$	—	9	12	Ω	$I_D = 1 \text{ A}$ $V_{GS} = 15 \text{ V}^{*1}$
Forward transfer admittance	$ y_{fs} $	0.45	0.75	—	S	$I_D = 1 \text{ A}$ $V_{DS} = 20 \text{ V}^{*1}$
Input capacitance	Ciss	—	990	—	pF	$V_{DS} = 10 \text{ V}$
Output capacitance	Coss	—	125	—	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	—	60	—	pF	$f = 1 \text{ MHz}$
Turn-on delay time	$t_{d(on)}$	—	17	—	ns	$I_D = 1 \text{ A}$
Rise time	t_r	—	50	—	ns	$V_{GS} = 10 \text{ V}$
Turn-off delay time	$t_{d(off)}$	—	150	—	ns	$R_L = 30 \Omega$
Fall time	t_f	—	50	—	ns	
Body to drain diode forward voltage	V_{DF}	—	0.9	—	V	$I_F = 2 \text{ A}$, $V_{GS} = 0$
Body to drain diode reverse recovery time	t_{rr}	—	1750	—	ns	$I_F = 20 \text{ A}$, $V_{GS} = 0$, $di_F / dt = 100 \text{ A} / \mu s$

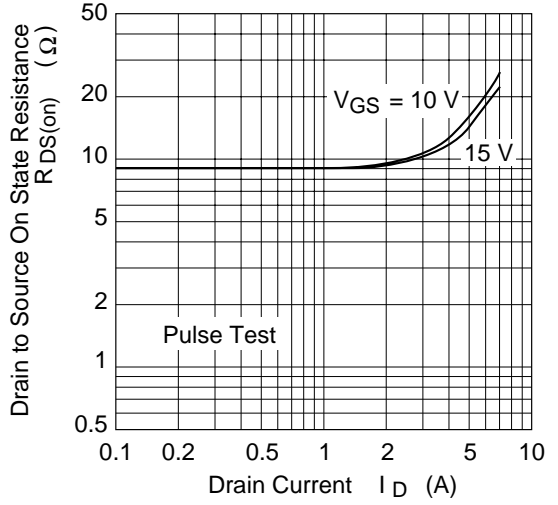
Note 1. Pulse Test



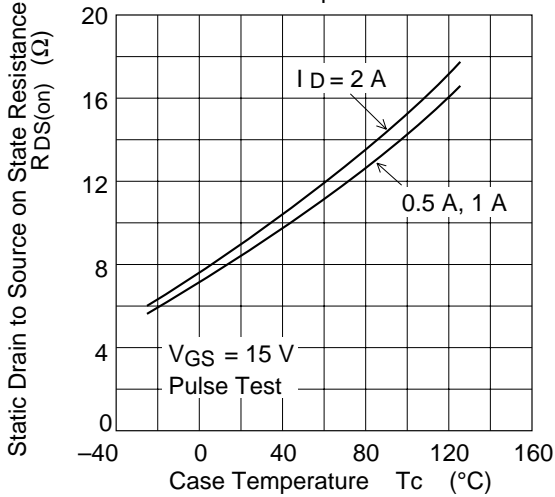
Drain to Source Saturation Voltage vs. Gate to Source Voltage



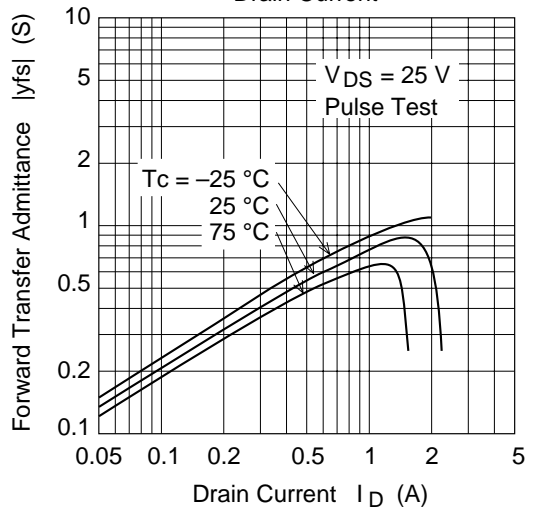
Static Drain to Source State Resistance vs. Drain Current

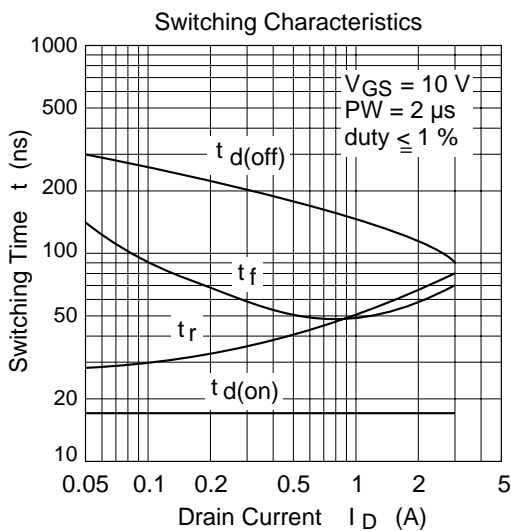
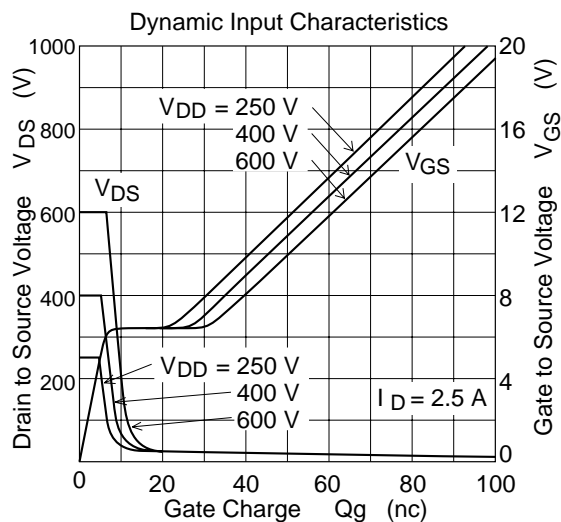
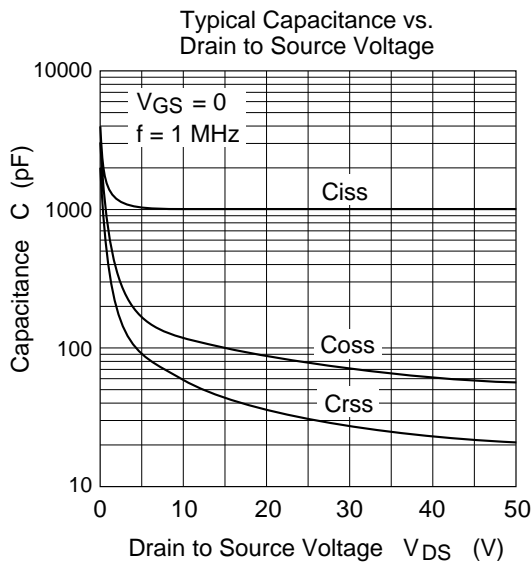
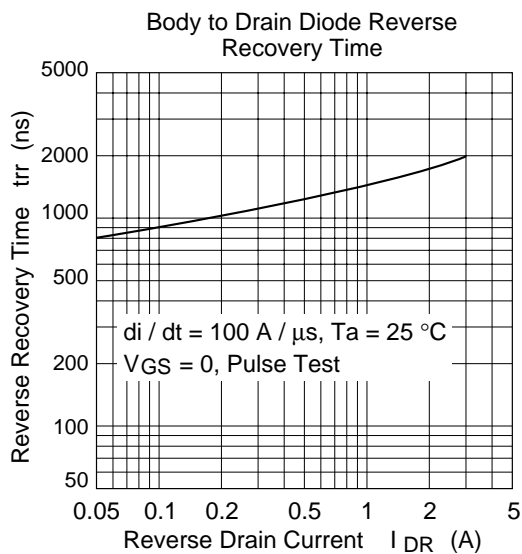


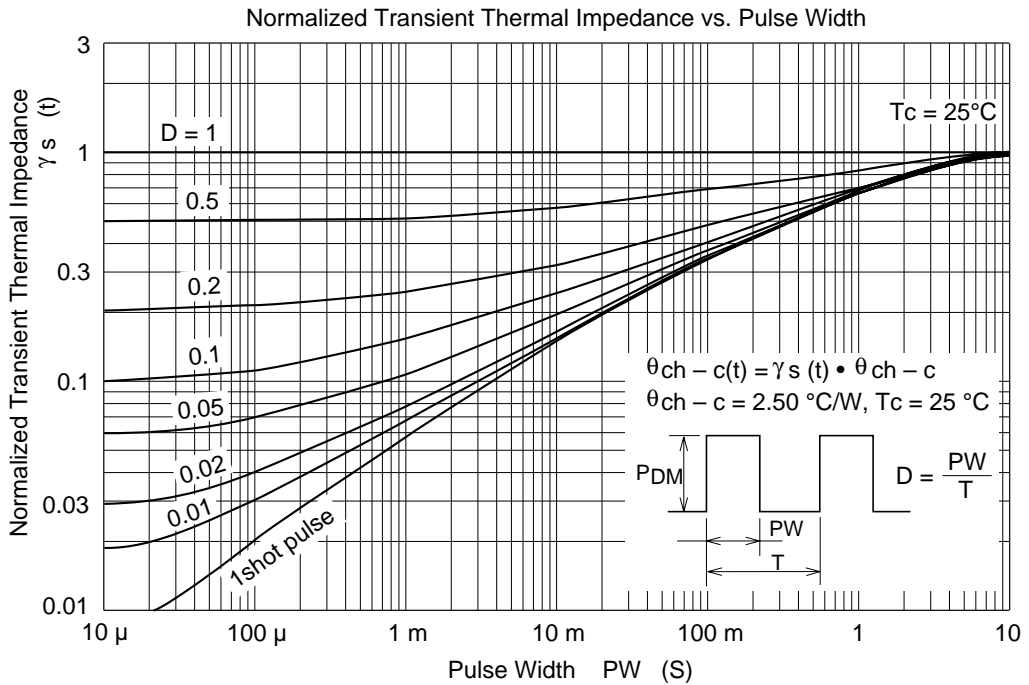
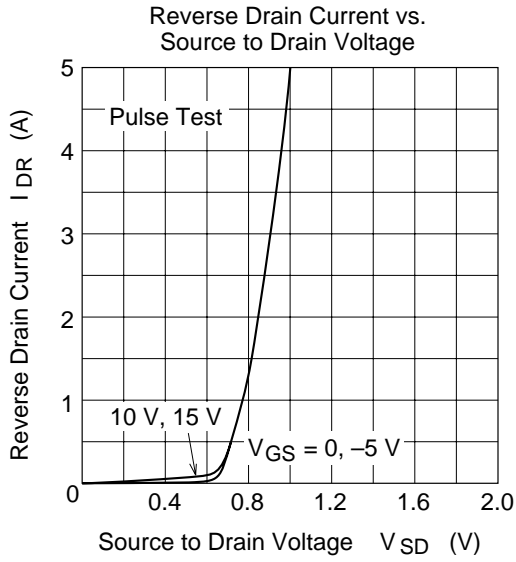
Static Drain to Source on State Resistance vs. Temperature



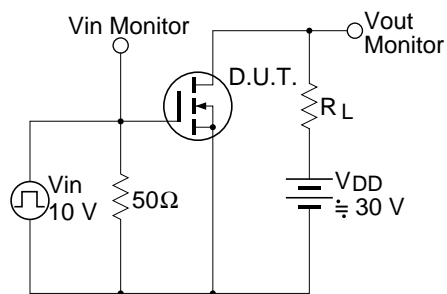
Forward Transfer Admittance vs. Drain Current



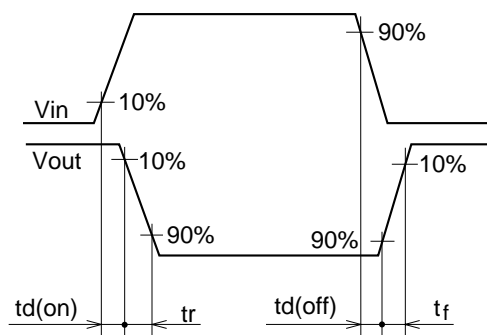


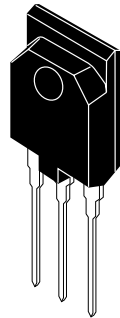
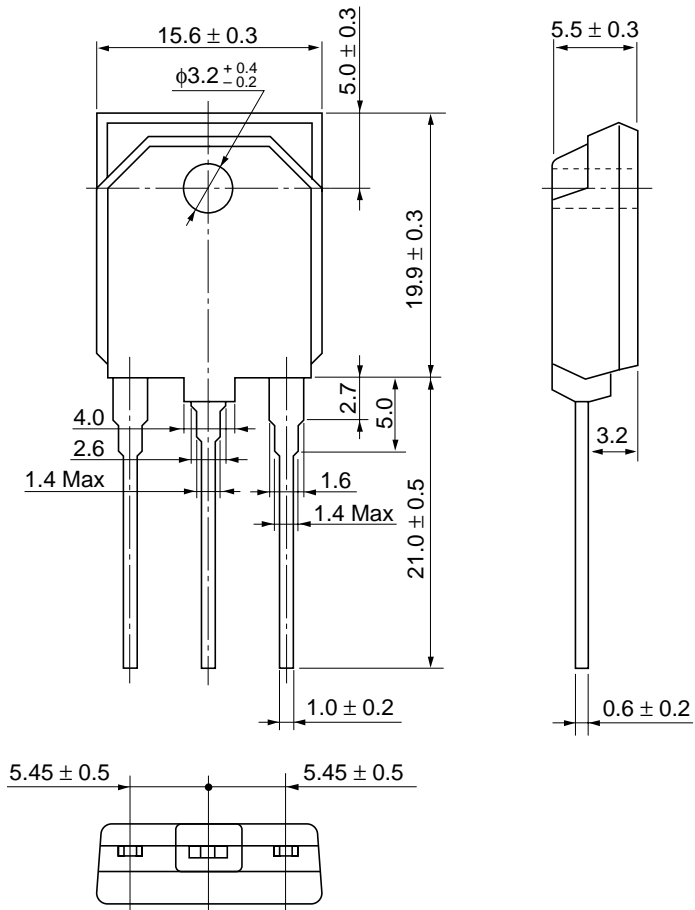


Switching Time Test Circuit



Waveform





Hitachi Code	TO-3PFM
JEDEC	—
EIAJ	—
Weight (reference value)	5.6 g

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